I, Michael Lebby, Ph.D., declare as follows:

1. I have been asked by counsel for Defendants Uber Technologies, Inc. ("Uber"), and Ottomotto LLC ("Otto") and Otto Trucking LLC (collectively, "Defendants") to provide certain opinions in the above-captioned case in connection with Waymo LLC's ("Waymo")¹ Reply In Support of Its Motion for a Preliminary Injunction ("Reply") and the Reply Declaration of Mr. Gregory Kintz in Support of Waymo's Motion ("Kintz Reply Declaration"). I submit this declaration in support of Defendants' Sur-Reply to Waymo's Motion. I have personal knowledge of the facts set forth in this declaration and, if called to testify as a witness, could and would do so competently.

I. MATERIALS CONSIDERED

2. In forming my opinions and views expressed in this declaration, I have reviewed and considered Waymo's Reply brief, the Kintz Reply Declaration, the deposition transcript of Mr. Kintz ("Kintz Dep. Tr."), the deposition transcript of Daniel Gruver ("Gruver Dep. Tr."), Supplemental Declaration of James Haslim ("Supplemental Haslim Declaration") and exhibits, the Supplemental Declaration of Scott Boehmke ("Supplemental Boehmke Declaration") and exhibits, the materials identified in my opening Declaration, and other materials and information that are identified in Exhibit 1 to my opening Declaration and referenced in my opening Declaration. I have also spoken with Mr. Haslim and inspected the Fuji device and the Spider components in person. In addition, I reviewed the fifty Waymo files attached as Exhibit 27 to this Declaration.

II. DIFFERENCES BETWEEN THE FUJI AND GBR3

3. Mr. Kintz opines in Paragraph 38 of his Reply Declaration that I failed to counter his opinion that the Fuji transmit printed circuit board (PCB) was a scaled-up version of the GBr3 design. According to Mr. Kintz, I only stated that the Fuji PCB edges have different curvatures than the GBr3 edges. I disagree. In Paragraphs 60 to 62 of my opening Declaration, I identify many differences between the Fuji PCB and the GBr3 PCB. I also state in Paragraph 62 of my

Supplemental Lebby Decl. ISO Defendants' Sur-Reply to Waymo's Preliminary Injunction Motion Case No. 3:17-cv-00939-WHA

¹ As used in this declaration, the term "Waymo" includes Google.

1	declaration that a comparison of the diode location and angle information for the Fuji in Haslim
2	Declaration Ex. B and the GBr3 in Jaffe Declaration Ex. 2 shows that the two systems were
3	designed for different fields of view and have different positioning of diodes.
4	4. Mr. Kintz failed to make the same comparison of the actual diode location and
5	angle information for all the boards that I did, and he conceded at deposition that
6	
7	(Ex. 2, Kintz Dep. Tr. at 99:13-23.) Instead, in Paragraph 38 of his Reply
8	Declaration, he continues to opine that of the GBr3,
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11	(At his deposition, Mr. Kintz
12	acknowledged that the
13	. (See Ex. 2, Kintz Dep. Tr. at 38:16-22.))
14	5. Mr. Kintz is wrong about Fuji's focal length. As stated in Exhibit E (Fuji beam
15	spacing and angle summary) to the April 7, 2017 Declaration of Mr. Haslim, the focal length of
16	the Fuji is 150 mm. (Haslim Decl. Ex. E at 3
17	11.) Mr. Kintz's
18	(Ex. 2, Kintz Dep. Tr. at 40:11-20.) Mr. Kintz
19	for the Fuji would
20	result in an incorrect calculation of the between the GBr3 and Fuji's boards. (Ex. 2, Kintz
21	Dep. Tr. at 46:14-18.) Because Mr. Kintz's calculations assume the wrong focal length for the
22	Fuji, his opinion that the Fuji transmit board is a "scaled up version" of the GBr3 board is invalid.
23	6. As noted in Paragraph 62 of my original declaration and further explained below,
24	the diode angles and angular spacing in Fuji and GBr3 are entirely different.
25	7. Some of the most notable differences between the Fuji and GBr3 designs in critical
26	parameters include: (1) different vertical field of view (FOV); (2) different focal length; (3)
27	different vertical angles for nearly every laser diode on every transmit board; (4) different angular
28	delta between diodes: (5) different minimum spacing between diodes: and (6) different layout of

components and conductive tracks. I summarize some of these differences in the chart below, 1 2 including an exemplary comparison of one board from the GBr3 3 one board from the Fuji mid-range cavity 4 GBr3 LiDAR Fuii LiDAR Block 5 Configuration Vertical FOV Medium: -22° to -4.22° (total 17.78°) Long: -3.92° to 8.23° (total 12.15°)

Total: 30.23°⁵ 6 7 -12° Cavity Tilt Focal Length 150mm['] 8 Diode Spacing 9 10 Diode Angles 11 12 13 14 15 16 Minimum Diode 3mm 17 Spacing Diode Pattern 18 19 20 2 Kintz Decl. ¶ 38. 21 Haslim Decl. ¶¶ 7, 11. 22 Jaffe Decl. Ex. 1 ¶ 38. Haslim Decl. ¶ 15. 23 Kintz Decl. ¶ 47 Haslim Decl. Ex. E at 3); Supp. Haslim Decl. ¶ 11. 24 Jaffe Decl. Ex. 2 at 16. From the table entitled 25 Haslim Decl. Ex. B. Angles for boards A-F are in the "theta" columns. Based on my conversation with Mr. Haslim, signs shown for angles in boards A-C are reversed (i.e., positive is 26 negative and vice-versa). Jaffe Decl. Ex. 1 ¶ 4. Haslim Decl. ¶ 11.

Jaffe Decl. Ex. 2 at 16.

Haslim Decl. ¶ 13. 27 28

III. WAYMO'S NEW TRADE SECRET ALLEGATIONS

8. Mr. Kintz opines in Paragraphs 55-79 of his Reply Declaration that Uber's LiDAR devices use additional trade secrets that were not identified in his original Declaration. In the paragraphs below, I respond to Mr. Kintz's opinions with respect to these new trade secret allegations.

A. Waymo claims:

- 9. Mr. Kintz states in Paragraphs 56 to 57 of his Reply Declaration that the concept is a Waymo trade secret. I disagree with Mr. Kintz. The use of is a known design choice in the field of diode lasers and has been discussed in public literature.
- Bond pads and other submounts for diode lasers are used to ensure proper mounting of the diode on the substrate and facilitate adequate thermal contact. The is well-known. U.S. Patent No. 5,940,277 describes how "[b]ond pads 14a, 14b, 14c, etc. may be disposed a short distance from edge 15, or their lower edges may be flush with edge 15." (Ex. 3, '277 patent at 3:55-58, Figure 1a.) U.S. Application No. 2007/0158807 discloses "a plurality of metal pads on the [top/bottom] surface extending to an outer edge of the [top/bottom] surface." (Ex. 4, '807 application, Claim 1.)
- 11. The Liu Textbook discusses the properties of submounts and discloses an example of a of the substrate. Fig. 7.32 (p. 212), excerpted below, shows a laser chip placed on a of the underlying substrate. (Ex. 4 to opening Declaration at 212.)

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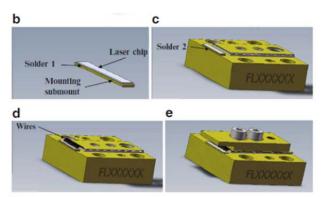
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12. A specification sheet for the a PCO-7110 laser diode drive module from Directed Energy, Inc. describes how, "[t]o facilitate different packages and mounting preferences, there are two solder pads on the end of the board to accept various laser diode packages mounted on axis to the driver." (Ex. 5, PCO-7110 manual at 2.) Figure 3 shows how the

on the in an axial mount position.

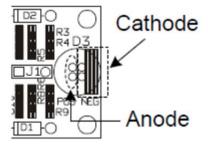


Figure 3. Cathode and Anode Pads on the PCB

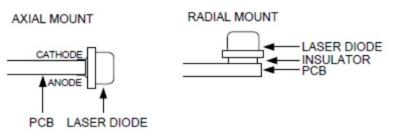


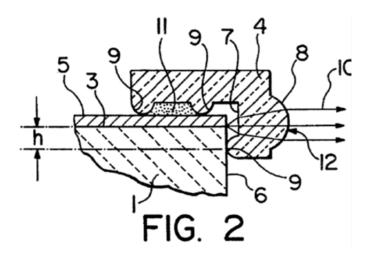
Figure 5. Axial and Radial Mounting Positions

13. Furthermore, I have reviewed the supplemental declaration of Mr. Boehmke, and he describes a circuit board layout created at Uber on March 29, 2016, before Uber's acquisition of Otto. As illustrated below in Figures 5.A and 5.B from the Supplemental Boehmke

Declaration, this circuit board layout placed the 1 2 (Figure 5.B is an enlarged version of a portion of Figure 5.A.) (Supp. Boehmke Decl. ¶ 8.) 3 3 laser diodes and Printed circuit 3 bond pads board (PCB) 4 Printed circuit 3 laser diodes on bond pads board (PCB) (2.3 mm spacing) 5 6 7 8 9 10 11 Figure 5.A Figure 5.B 12 13 14. This design demonstrates Uber's independent development of 14 shows that Uber did not use Waymo's alleged trade secret. 15 В. 16 Waymo claims: 17 18 19 15. Mr. Kintz states in Paragraphs 58 to 63 of his Reply Declaration that the concept 20 21 is a Waymo trade secret. I disagree with Mr. Kintz. 22 16. As I discussed in Paragraph 66 of my opening Declaration, the use of 23 such as fast-axis collimating (FAC) lenses, is commonplace in the design of laser systems. 24 (At deposition, Mr. Kintz 25 " (Ex. 2, Kintz Dep. Tr. at 106:25-107:6.)) There 26 are numerous vendors that sell FAC lenses and the use of such lenses in connection with laser 27 diodes is widely known and disclosed even in publicly-available vendor specifications, such as 28

1	the one I referenced from Hamamatsu. In response, Mr. Kintz opined that
2	qualifies as a trade secret.
3	17. First, I note that neither Mr. Kintz nor Waymo's Trade Secrets List identifies the
4	specific Waymo claims to be a trade secret. Instead, Mr. Kintz
5	only states that the steps include "an that results in a
6	that is
7	(<i>Infra</i> , ¶¶ 59, 62.) Mr. Kintz
8	. Injection molding to create lenses is a well-known technique in
9	optical component manufacturing. 15 As Mr. Kintz stated during deposition,
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11	. (Ex. 2, Kintz Dep. Tr. at 203:5-204:4; '922 patent
12	at 15:19-20, 15:50-55.) Instead, he appears to claim that
13	. I disagree.
14	18. U.S. Patent No. 5,420,722, which issued on May 30, 1995, discloses a "cylindrical
15	microlens [] mounted directly to a laser diode die." (Ex. 6, '722 patent at 1:59-60.) The shape
16	and positioning of the microlens is illustrated in Figure 2, reproduced below. The laser diode
17	(1) emits laser light along the arrow lines indicated in the figure. The cylindrical microlens (4) is
18	shaped so as to be mounted over the top and in front of the laser diode. The patent states:
19	"Microlens 4 is permanently bonded to die 1 using an adhesive 11." (<i>Id.</i> at 2:5-7.) The microlens
20	has a cylindrical surface (8) that collimates the laser light emitted from the diode. The patent
21	notes that the invention "can be used with molded lenses." (<i>Id.</i> at 2:41-43.)
22	
23	¹⁴ In fact, the GBr3's Kintz Dep. Tr. at 198:1-11.)
24	Millions if not billions of injection-molded lenses that are positioned in front of laser diodes can be found in common optical storage products today. These would include CD players,
25	DVD players, and Blu Ray players, where the semiconductor laser diode emits light that passes through an injection-molded optical lens before reaching an optical disk. Plastic-based injection-
26	molded lenses are a huge industry for many different industrial, consumer, and technical markets and can be found in many products where volumes of lenses are significant. Good examples of
27	the use of highly accurate, low cost, injection-molded optical lenses that specifically deal with laser diode emission in both the fast and slow axis, as well as collimation, are found in fiber optic

communications, as well as the high power laser diode writing, scribing, and engraving industry.



19. The shape of the microlens in the '722 patent is

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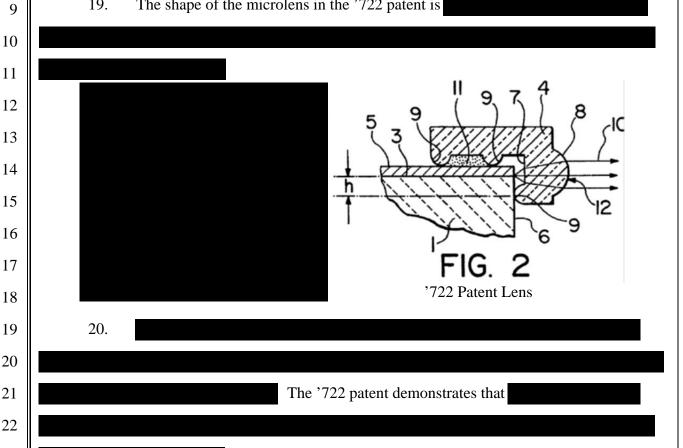
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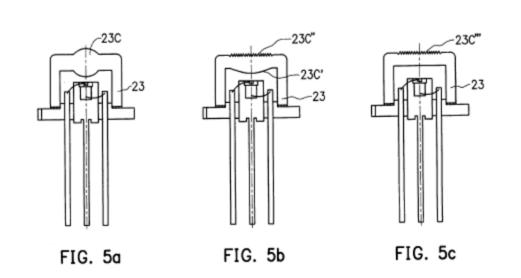
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21. U.S. Patent No. 5,825,054, which claims priority to December 29, 1995, discloses how "[t]he coupling process of the semiconductor laser and the focusing lens can be accomplished before sealing all parts on the header within a cap, thus providing the semiconductor laser apparatus with high output power." (Ex. 7, '054 patent at 2:16-21.) The "cap can be formed by injection molding transparent acrylic resin such as PC or PMMA and

coating AR (anti-reflection)-coated on both sides of the front end of the cap" and "on the top (i.e., the front end) of the cap, different kinds of lens, such as a spherical lens, aspherical lens and Fresnel lens, can be formed for collimating and focusing." (Ex. 7, '054 patent at 2:33-39.) As illustrated in Figure 3a, a transparent cap 23 is mounted in front of the semiconductor laser chip 26, and "[t]he manner of sealing the apparatus as shown in FIG. 3a is to fit the inner circumference of the cap 23 to the flange of the plastic-molded header 22," which is then sealed by epoxy 24. (*Id.* at 3:33-35.) Figures 5a, 5b, and 5c, for example, illustrate mounting a spherical or aspherical convex lens, a spherical convex lens and a holographic film, and a Fresnel lens respectively. These figures

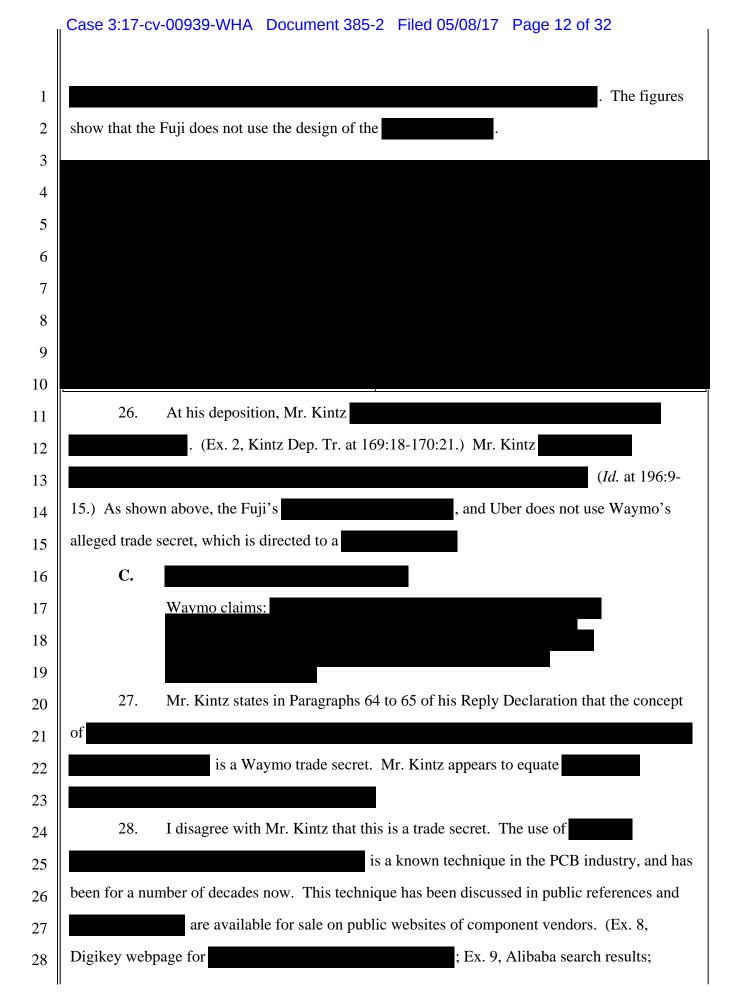


- 22. The laser diode light emission passes through the injection-molded lens for optical lensing. The cap is designed to be positioned beside the laser emission path and is aligned into position and then attached to the package via epoxy 24. This type of package is commonplace in the laser diode industry and the basic design was first used in the 1950s and 1960s. The package is called a TO-header where the letters TO stand for Transistor Outline. Over the years, the package has become so popular that the original structure has been used as the work horse for lasers, LEDs, photodetectors, and transistors.
- 23. Ever since the first semiconductor room temperature laser diode was demonstrated by Bell Labs in the late 1960s, engineers have been aware of how laser light is emitted from the

1	chip. The issues of fast axis, slow axis, collimation and focusing were well known principles in			
2	optics even before the semiconductor laser diode chip was demonstrated. Using a lens in front of			
3	a laser chip is part of an optical engineer's basic skill set, as the light diverges quickly and optics			
4	are needed to efficiently utilize the emitted light. In the 1970s, glass lenses were used, but as			
5	laser diodes entered high-volume manufacturing with products such as CD players in the 1980s,			
6	the drive to lower costs, miniaturize size, and increase functionality meant the optics industry			
7	quickly developed injection-molded techniques to manufacture lenses. Engineers have used			
8	optical lenses for LiDAR systems for over 20 years knowing that they have a choice of materials			
9	to utilize that include glass, plastic, and other materials such as sapphire. The use of injection-			
10	molded plastic lenses has been successful in products that require reduction in costs, and which			
11	need to scale to high volume and the choice for injection-molded lenses in LiDAR is obvious to			
12	any optoelectronics engineer today.			
13	24. I understand from reviewing the Supplemental Declaration of James Haslim that			
14	the on the Fuji transmit boards have the following features that differentiate them			
15	from : (1) ; (2)			
16	; and (3)			
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18	TS List No. 9). The drawing of the Fuji is reproduced below.			
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25	25. Below, the figure on the left is the in the GBr3, which is designed to			
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(Jaffe Decl. Ex. $1 \P 9$.) On the right is

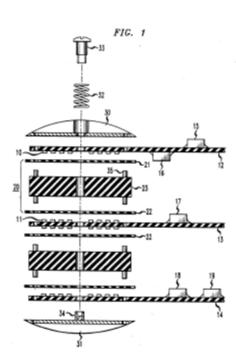
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1	Ex. 10, Amazon webpage for
2	utilizes a PCB, the PCB is positioned and raised from the case, module, shell, box etc. in which it
3	is disposed. In order to raise the PCB, are used. If two PCBs are used, then each PCB is
4	stacked using . Catalogs from distributors such as DigiKey, which is a large distributor of
5	electronic components and parts, have pages of different kinds of PCB in different
6	materials (e.g., steel, brass, aluminum), shapes, and sizes. PCBs is not new – it is a very
7	common technique practiced by many electronics companies around the world today. Mr. Kintz
8	has acknowledged at deposition that
9	. (Ex. 2, Kintz Dep. Tr. at 232:23-
10	233:3.)
11	29. The illustration below from <i>Printed Circuit Boards</i> : <i>Design, Fabrication</i> ,
12	Assembly and Testing, a publicly-available reference authored by R. S. Khandpur, shows
13	. (Ex. 11.)
14	Printed circuit
15	board
16	Chassis
17	Spacer posts
18	(b) Mount on tapped spacers
19	Any size board can be accommodated by this simple mounting. It can be a space-saver on walls and doors of enclosures.
20	or cholosards.
21	30. U.S. Patent No. 5,334,029 explains that, for "stacked arrays of printed circuit
22	boards with integrated circuit (IC) and other components mounted thereon," the use of a "spacer
23	is required to ensure sufficient board separation to accommodate the components and to allow for
24	cooling air flow." (Ex. 12, '029 patent at 1:8-17.) Figure 1 illustrates the use of spacer elements
25	23 to connect stacked circuit boards 12, 13, and 14.
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31. The concept of is also not a trade secret. Many PCB designs have different thicknesses, especially if highly complex electronic and optoelectronic layouts for circuits are necessary. For example, a simple electronic and optoelectronic circuit may require only a 1, 2 or 3 level PCB. This means that only 1, 2 or 3 metal layers are needed in the composition of the PCB. Other more complex circuit designs may require 7, 8, 9, 10 or even more levels of metal as part of the composition of the PCB. In this case, the board is much thicker, probably stiffer, and more expensive. In today's world, the size, complexity, thickness, and ultimate composition of the PCB is a major feature in the overall product design. Thickness is one of the parameters that all engineers are aware of when they design and specify PCB boards from manufacturers. In fact, the number of metal levels, thickness, and composition are typically part of the technical specification engineers draw up when ordering PCBs. When PCBs are stacked together, for fiber optic communications (optical switches, optical serves, backplanes, racks, etc.), LiDAR, or any other optoelectronic system, the thickness of PCBs is a critical specification that needs to be addressed early in the design.

32. In the context of using in a system for conveying PCBs along an assembly line, U.S. Patent No. 6,863,170 is directed to a method of "selecting said spacer from a plurality

1	of spacers as a function of its thickness and a thickness profile of said printed circuit board" and
2	installing the . (Ex. 13, '170 patent at Claim 1.)
3	33. U.S. Patent No. 8,593,828, the application for which was published on August 4,
4	2011, discloses PCBs separated by that permit slight movement of the PCBs to ensure
5	proper positioning "when tolerances are tight." (Ex. 14, '828 patent at 16:19-22.) Fig. 26A
6	shows ("standoffs 196") separating two PCBs (86). The patent discloses that "the
7	standoff 196 is allowed to float about the top PCB 86A to allow the positioning or orientation of
8	the top PCB 86A to move slightly in the X, Y, or Z directions with regard to the bottom PCB
9	86B." (<i>Id.</i> at 16:43-47.)
10	202 - M
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12	IN IS
13	FIG. 26A
14	184 7 Y
15	I .
16	34. As explained above, the use of
17	, is well known and not a trade
18	secret.
19	D.
20	Waymo claims:
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24	35. Mr. Kintz states in Paragraphs 67 to 71 of his Reply Declaration that the concept
25	of is a Waymo trade secret. I disagree with Mr. Kintz. The use
26	of an is a known technique in LiDAR and other
27	optical systems. This technique has been discussed in patent literature and
28	are available for sale on public websites of component vendors. (Mr. Kintz

(Ex. 2, Kintz 1 2 Dep. Tr. at 205:21-24.)) 3 36. U.S. Patent No. 7,187,823, which has a priority date of March 16, 2004, discusses 4 a solution to "overcome deficiencies in existing scanning systems by changing the way in which 5 power and information are transmitted between rotary and stationary portions of a system." 6 (Ex. 15, '823 patent at 4:40-44.) The scanning systems in question include "LiDAR systems." 7 (*Id.* at 1:35-53.) The '823 patent discloses using an optical link "[i]n order to allow an optical 8 signal to be passed between a data interface 422 of a stationary portion of the FDV and an optical 9 transceiver 420 in a rotary frame, for example, which can be rotatable with respect to each other." 10 (*Id.* at 7:7-10.) 37. This optical link is "a single optical fiber 414," where "[t]he fiber can be a single, 11 12 continuous fiber, or can consist of a first fiber portion 414 and a second fiber portion 416" that 13 "connect through a rotary connection . . . allowing the portions of the fiber to rotate with respect to one another while allowing for a common light path." (*Id.* at 7:20-27.) In other words, the 14 15 '823 patent discloses 16 17 18 38. The '823 patent provides figures to illustrate 19 20 illustrated in Figure 5, an can be used "to transfer information between an optical transceiver 512 and data interface 514." (*Id.* at 8:21-23.) 21 22 Transceive <u>512</u> 23 Power Electronics 516 24 510 25 26 Interface Power Electronics 27 FIG. 5 28

1	39. The '823 patent also shows the use of a .
2	Figure 7a shows "a first fiber portion 700 and a second fiber portion 706" that with a
3	comprising "an accepting connection member 704" and "a projecting connection
4	member 710, shaped to be received by the accepting connection member 704." (<i>Id.</i> at 7:36-50.)
5	
6	706
7	702
8	
9	704 710
10	700
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12	FIG. 7(a)
13	40. A quick look on the Internet for only a few minutes generated a long list of
14	vendors that can supply for varying prices and specifications. Such vendors
15	include the following:
16	Princetel (for http://www.princetel.com/product_forj.asp (Ex. 16.)
17	Moog: http://www.moog.com/products/fiber-optic-devices/fiber-
18	optic-rotary-joints/ (Ex. 17.)
19	Thorlabs (for https://www.thorlabs.com/newgrouppage9.cfm?objectgroup_id=75
20	56 (Ex. 18.)
21	Doric (for sciences/193-tiber-optic-rotary-joints (Ex. 19.)
22	
23	Laser components (): http://www.lasercomponents.com/de-en/product/fiber-optic-rotary-inints/ (Fig. 20)
24	<u>joints/</u> (Ex. 20.)
25	41. From my review of the Supplemental Declaration of James Haslim and my
26	conversation with Mr. Haslim, I understand that Uber has purchased off-the-shelf
27	from Princetel for its Fuji LiDAR.
28	

43. A number of publicly available references discuss the use of For example, the diagram below is publicly available from a 2011 paper titled "Controlling the 1 µm spontaneous emission in Er/Yb co-doped fiber amplifiers," and it describes using an (Ex. 23.)

> doped fiber DFB seed 99/1% WDM WDM 1550 nm Isolator Isolator Coupler Coupler Coupler Pump LDs $\lambda = 980 \text{ nm}$ Back-scattered 1st stage output P = 650 mW light monitor power monitor FC/APC Pump LD Connector end $\lambda = 975 \text{ nm}$ Tap = 10 W Mode-1064/1550 1064/1550 Isolator coupler stripper 99.9% WDM WDM Double-Clad Output Pump 0.1% Er^{3+}/Yb^{3+} Combiner doped fiber Forward Backward (to OSA) 1064 nm 1064 nm emission emission

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44. as illustrated above, generates more optical power than single-stage amplification. The reason engineers choose is that they need higher stability with increased optical output power emerging from the seen in the figure above, all fiber amplifiers have a source laser and pump lasers – in this case the source or pump laser is a DFB 1550nm laser. DFB stands for "distributed feedback" laser and has properties of narrow linewidth and high performance. The pump laser diodes have a shorter wavelength (980nm) and are also coupled into the main optical channel with the 1550nm DFB laser. The light entering the first amplifier is composed of both 1550nm and 980nm light. The 980nm light excites the in the glass fiber and promotes optical gain or amplification of the light. In some systems, the optical output power level of amplified optical light is enough using only one amplifier, but

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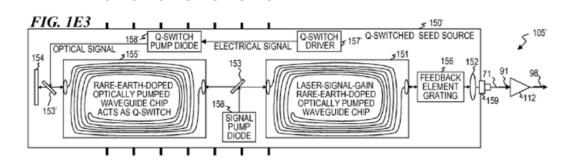
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is popular, especially in

LiDAR, laser cutting, and fiber communications. The light from the first amplifier is coupled to

1	the entrance of the , and pump laser diodes are again used to further increase the	
2	optical gain of the signal. In the , high-output pump laser diodes are used, and the other	
3	are used to further increase the performance of the	
4	the industry, another	
5	. Using has been	
6	developed over a number of decades, and is a standard approach for design.	
7	The optical output power level emerging from the is higher than the first, and,	
8	depending on the system design, can be used as a high power source for optical processing with	
9	high levels of stability.	
10	45. U.S. Patent No. 8,934,509 discloses enabling "higher-pulse-energy signals that	
11	provide a longer range for illuminators for long-range image-acquisition systems (illuminating	
12	scenes for cameras), and improved light-distancing-and-ranging (LIDAR) systems." (Ex. 24,	
13	'509 patent at 9:14-18.) In particular, the patent discloses: "a semiconductor laser diode 158',	
14	and the signal-amplifier planar waveguide optical amplifier 155' is doped with Er (erbium) or co-	
15	doped with YbEr (ytterbium and erbium) that amplifies signal light of about 1550 nm when its	
16	pump light is supplied by semiconductor laser diode 158." (<i>Id.</i> at 25:3-7.) This is shown in	
17	Figure 1E3 below. The patent also describes an alternative embodiment, illustrated in Figure 1F3	
18	(not shown), where "the power amplifier is an erbium-doped fiber amplifier (EDFA) or an	
19	erbium-ytterbium co-doped fiber amplifier (EYDFA)." (<i>Id.</i> at 29:44-46.)	
20	46. As explained in the '509 patent, when "supplied with sufficient optical pump light	
21	from Q-switch pump source 158', optical amplifier 155' becomes transparent to, or amplifying of,	
22	light of the signal wavelength and the Q-switch is 'on.'" (<i>Id.</i> at 24:41-45.) When the Q-switch is	
23	on, "lasing begins and the stored energy in [rare earth dopant ions in] optical-gain medium 151 is	
24	output as seed signal pulse 91." (Id. at 24:50-52.)	
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47. Based on my review of the Supplemental Declaration of James Haslim and my conversation with Mr. Haslim, Uber purchased off-the-shelf

from publicly known vendor iXblue for the Spider. 16

IV. MR. KINTZ'S SUPPLEMENTAL OPINIONS ON WAYMO'S ORIGINAL TRADE SECRET ALLEGATIONS

48. As I discussed above, Mr. Kintz ignores the many quantitative differences in critical parameters between the Fuji and GBr3 boards. Instead, he focuses on broad concepts that he claims are Waymo's trade secrets—

. None of these concepts, however, are trade secrets. The general features that Waymo claims as its own are known design choices in the fields of LiDAR and diode lasers. Below, I address supplemental opinions that Mr. Kintz provided for the first time in his Reply Declaration.

A. of Diodes (TS List No. 1)

49. Waymo claims:

As Dr. McManamon

explained in his Declaration, this concept is not a trade secret because the idea of having

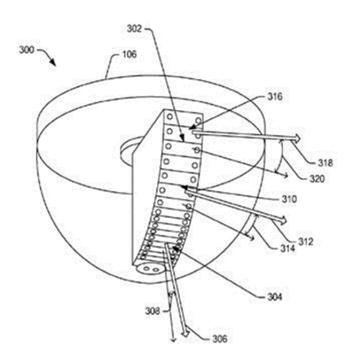
I also note Mr. Kintz said

(Ex. 2, Kintz Dep. Tr. at 231:24-232:2.)

 $^{^{16}}$ Based on my conversation with Mr. Haslim, my inspection of the Spider components, and the Haslim Supplemental Declaration, the Spider was a fiber laser design, and Uber only built a few components before abandoning the design. Uber never built all the components, assembled all the parts, or created a functional prototype. (Haslim Supp. Decl. \P 2.)

1	was known to LiDAR designers who were completely independent of Waymo,
2	including Mr. Boehmke and Velodyne.
3	50. In his Reply Declaration, Mr. Kintz opines that the work of Mr. Boehmke and
4	Mr. Haslim was not an independent development of the
5	explain below, Mr. Boehmke and Mr. Haslim's documents show their independent work.
6	51. Mr. Boehmke developed a laser diode design in 2015. His
7	October 2015 "LADAR Design Notebook" shows a pattern of 32 diodes, with the
8	. (Supp. Boehmke Decl.
9	¶ 3 (annotated Figure 1 reproduced below).) An accompanying chart shows the precise
10	parameters (angles and deltas).
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23	52. In December 2015, Boehmke sent a LiDAR scan pattern with horizontal
24	lines showing of the laser beams produced by the diodes, as shown in the
25	annotated figures below. (Id. ¶ 4, Figure 2.A, Figure 2.B.)
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27	
28	

1	Decl. ¶¶ 54-58.) Waymo argues that the '190 patent does not teach
2	(Repl. 4.) That is incorrect – the patent teaches
3	in a single LiDAR system by choosing to include more diodes in certain parts of the
4	vertical FOV. ('190 patent at 6:45-56.) Waymo contends that the '190 patent "does not teach
5	any ," but it does teach
6	, which is
7	(Repl. 4.)
8	55. Though his opening Declaration only referred to , Mr. Kintz states
9	for the first time in his Reply Declaration that Waymo's trade secret is the concept of
10	, which he clarified to mean that
11	(Ex. 2, Kintz Dep.
12	Tr. at 63:6-14.) But even the concept of is known to the public. U.S.
13	Patent Application No. 2016/0291136, filed in 2015, describes a rotating LiDAR system with
14	"inconsistent spacing between LiDAR components," where each LiDAR component includes a
15	laser emitter and detector configured in a frame. (Ex. 25, '136 application at [0014], [0026].)
16	The application discloses first angle 308, second angle 314, and third angle 320, where each angle
17	is the angle between the direction of one LiDAR component (i.e. direction of the emitter diode)
18	and the direction of the adjacent LiDAR component. (Id. at [0026].) The application discloses an
19	embodiment where "the first angle 308 may be less than the second angle 314 and the second
20	angle 314 may be less than the third angle 320." (Id.) This description is the
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56. Furthermore, the Fuji does not use as defined by Mr. Kintz in his deposition. He stated that the (Ex. 2, Kintz Dep.

Tr. at 63:6-14.) He also said that

. (*Id.* at 63:15-64:14.) From the Supplemental

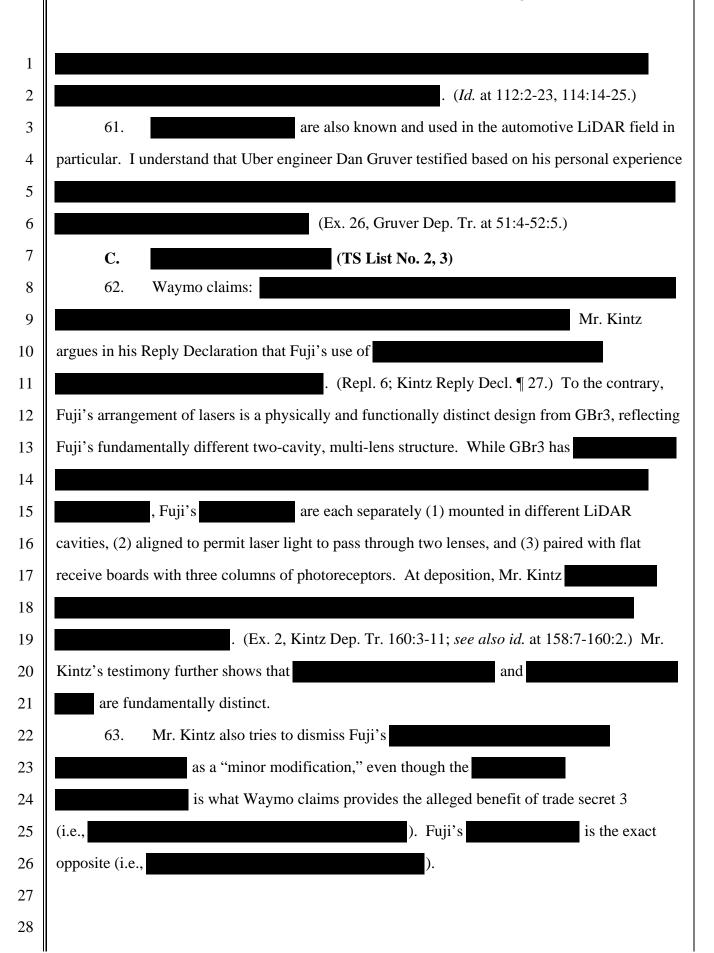
Declaration of James Haslim, I have identified the current beam angles in the Fuji's medium-range cavity (diodes on boards A-C) and long-range cavity (diodes on boards D-F) in the tables below. ¹⁹ Using these beam angles, I calculated the spacing (i.e. the "delta in degrees," or the difference in angle between one diode and the diode preceding it). ²⁰ As you can see below, most of the boards have portions where the

. In particular, the D-F boards for the long-range cavity have fairly uniform spacing across the entire boards. The A-C boards have portions where the

The difference in angle has been rounded to the second decimal point.

¹⁹ The beam angles for the medium-range cavity are adjusted for the negative 12-degree tilt of that cavity.

1	Nos. 6, 28-30, 39, 94-99, but these alleged trade secrets are directed to the GBr3's specific		
2	parameters, schematics, and design files. As I explained above, the Fuji and GBr3 boards were		
3	designed for different vertical fields of view and have many quantitative differences in critical		
4	parameters, including different vertical angles for nearly every laser diode on every transmit		
5	board and different angular deltas between diodes. It is my opinion that Uber is not using any of		
6	Waymo's alleged trade secrets Nos. 4, 6, 28-30, 39, 94-99.		
7	B. (TS List No. 7)		
8	58. Waymo claims:		
9	The concept of positioning a laser diode to		
10	is not a secret, as it is disclosed in public literature and used in Velodyne's LiDARs.		
11	59. As discussed in my opening Declaration at Paragraphs 49 to 51,		
12	are clearly illustrated and discussed in a 2015 textbook on semiconductor lasers and a		
13	2007 dissertation on laser diode systems (see figures and excerpts below):		
14	a N-contact laser bar		
15	Laser Die Mounting Substrate Solder solder heat sink		
16	Overhang		
17			
18	2015 Liu Textbook, p. 224 : "Overhang and underhang characterize the alignment between 2007 Scholz Dissertation, p. 63: "The laser bar is mounted with a small overhang on the		
19	the diode laser die (could be a single emitter chip or a bar) and the mounting substrate." top of the heat sink." (Ex. 4 to opening Declaration.)		
20	(Ex. 3 to opening Declaration.)		
21	60. Mr. Kintz argues in his Reply Declaration that the Liu Textbook teaches away		
22	from using an . (Repl. 5.) I understand, however, that in the law of trade secrets, public		
23	disclosure of the concept breaks the secret. Mr. Kintz also contends that the references do not		
24	disclose a (id.), but Mr. Kintz		
25	. (Ex. 2, Kintz Dep.		
26	Tr. 115:6-13.) Though Mr. Kintz		
27			
28	. (<i>Id.</i> at 123:4-8, 125:10-20.) Mr. Kintz also		



1	64. As I previously explained, once the choice was made to use (a number
2	that comes from Velodyne, not Waymo), ²² distributing those in a (or even
3) was an obvious configuration that designers would have considered in view of
4	known design considerations, and a
5	illustrated in the Liu Textbook. (Ex. 4 to opening Declaration at 111 (Figure 5.3).) Moreover,
6	Waymo's own '922 patent publicly discloses the use of four boards with 16 light sources on each.
7	('922 patent at 9:20-23.) Such distributions of lasers are part of general engineering know-how in
8	the diode laser field.
9	D. (TS List No. 14)
10	65. Waymo claims:
11	
12	Mr. Kintz argues in his Reply Declaration that
13	there is not a single reference that discloses using
14	. But U.S. Patent No. 4,244,109 discloses
15	(see Fig. 3,
16	below),
17	
18	in the second se
19	4 23
20	66. The patent also discloses that : "[T]he
21	photodiodes are mounted on the PCB in alignment with the two holes." (Ex. 6 to opening
22	Declaration, '109 patent at 3:27-28.) Mr. Kintz
23	. (Ex. 2, Kintz Dep. Tr. at 188:2-5.)
24	
25	
26	²² Mr. Kintz agrees that the use of 64 laser diodes in a LiDAR is in the public domain. (Ex. 2, Kintz Dep. Tr. at 101:21-23.)
27	I note that Waymo's Trade Secrets List says that the (Ex. 2, Kintz Dep. 11. at 101.21-23.) (Ex. 2, Kintz Dep. Tr. at
28	189:4-190:14.)

1	V.	REVIEW OF WAYMO AND UBER FILES
2		67. I understand that Waymo's counsel identified a list of top fifty files from among
3	the 14,	,000 files allegedly downloaded by Anthony Levandowski. (Ex. 27.) I have inspected the
4	fifty fi	les on a source code computer at the office of Waymo's counsel. The fifty files contain
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6		
7		
8		
9		68. The information in the fifty files is
10		that I previously
11	review	red. The fifty files do not cause me to change any of the opinions in my opening
12	Declar	ration.
13		69. I note that
14		
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18		70. I also note that the fifty files do not show how to use certain concepts in Waymo's
19	allegeo	d trade secrets. For example, the fifty files do not include information on
20		. The fifty files also do not show how to
21		. Though the
22		
23		. (At his deposition, Mr. Kintz
24		
25		. (Ex. 2, Kintz Dep. Tr. at 230:9-231:23.) ²⁴
26		71. In addition, I also reviewed nine unique Uber files that are hash-matched to some
27	of the	allegedly downloaded 14,000 files. I was able to open the .txt files (11200733.txt,
28		²⁴ He also (Id. at 220:12-221:2.)

Case 3:17-cv-00939-WHA Document 385-2 Filed 05/08/17 Page 31 of 32

Case 3:17-cv-00939-WHA Document 385-2 Filed 05/08/17 Page 32 of 32